2A STANDARD RECOVERY BRIDGE RECTIFIER

Product Summary

V_{RRM} (V)	I_F (A)	V_F Max (V) @ I_F = 1A	I_R Max (μA)
1000	2	1.1	5

Features

- Glass Passivated Die Construction
- Ideal for Printed Circuit Board
- Reliable Low Cost Construction Utilizing Molded Plastic Technique
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative.**
  https://www.diodes.com/quality/product-definitions/

Mechanical Data

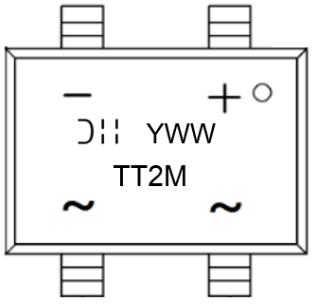
- Package: TTL
- Package Material: "Green" Molding Compound, UL Flammability Classification 94V-0, (No Br. Sb. Cl.) "Halogen-Free".
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 e3
- Polarity Indicator: As Marked on The Body
- Weight: 0.41 grams (Approximate)

Ordering Information (Note 4)

Part Number	Qualification	Package	Packing	
			Qty.	Carrier
TT2M-13	Commercial	TTL	1500pcs	Reel

Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



TT2M = Product Type Marking Code
= Manufacturers' Code Marking
YWW = Date Code Marking
Y = Last Digit of Year (ex: 1 = 2021)
WW = Week Code (01 to 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Maximum Repetitive Peak Reverse Voltage		V_{RRM}	1000	V
Maximum DC Blocking Voltage		V_{DC}	1000	V
Average Rectified Output Current	@T_A = +25°C (Note 5)	$I_{F(AV)}$	2.0	A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave	@T_A = +25°C @T_A = +125°C	I_{FSM}	75 60	A
Peak Forward Surge Current 1.0ms Single Half Sine-Wave	@T_A = +25°C @T_A = +125°C	I_{FSM}	150 120	A
I^2t Rating for Fusing (t = 8.3ms)		I^2t	14.9	A^2s
Operating and Storage Temperature Range		T_J ,T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Test Condition		Symbol	Typ	Max	Unit
Forward Voltage	I_F = 1A	T_A = +25°C T_A = +125°C	V_F	0.89 0.76	1.1 —	V
Leakage Current	V_R = 1000V	T_A = +25°C T_A = +125°C	I_R	0.1 22	5 500	µA
Typical Junction Capacitance (Note 6)			C_J	25		pF

Thermal Characteristics

Characteristic	Symbol	Typ	Unit
Typical Thermal Resistance (Without Heatsink)	$R_{\theta JC}$ $R_{\theta JL}$ $R_{\theta JA}$	30 10 50	°C/W
Typical Thermal Resistance (Note 7)	$R_{\theta JC}$ $R_{\theta JL}$ $R_{\theta JA}$	7 25 30	°C/W

Notes: 5. Perform static test after the temperature of oven is steady 20 minutes.
6. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.
7. Thermal resistance junction to case, lead and ambient in accordance with JESD-51.
Unit mounted on glass-epoxy substrate with 1oz/ft2 _ 10mm x 10mm copper pad per pin.

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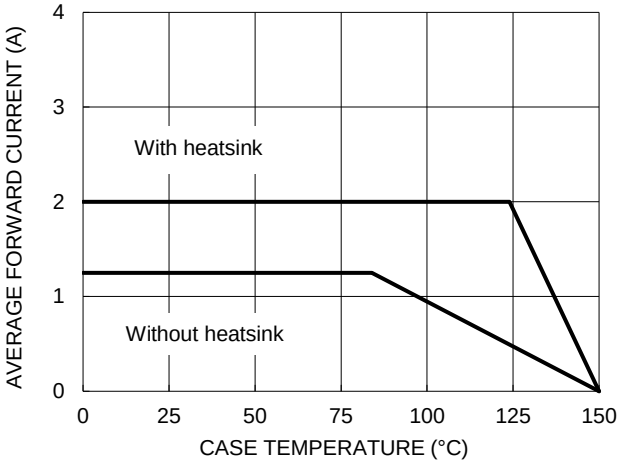


Figure 1. Forward Current Derating Curve

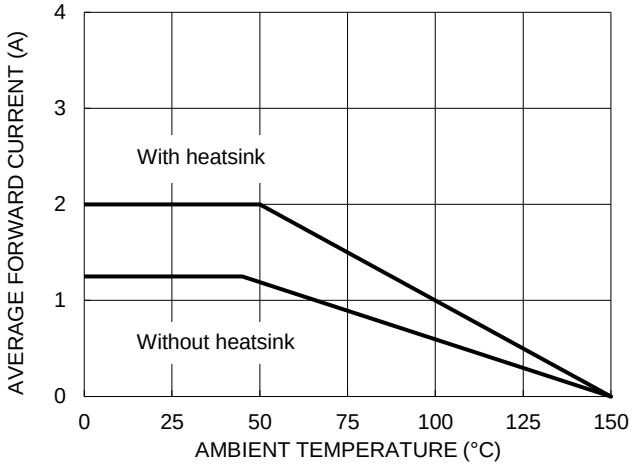


Figure 2. Forward Current Derating Curve

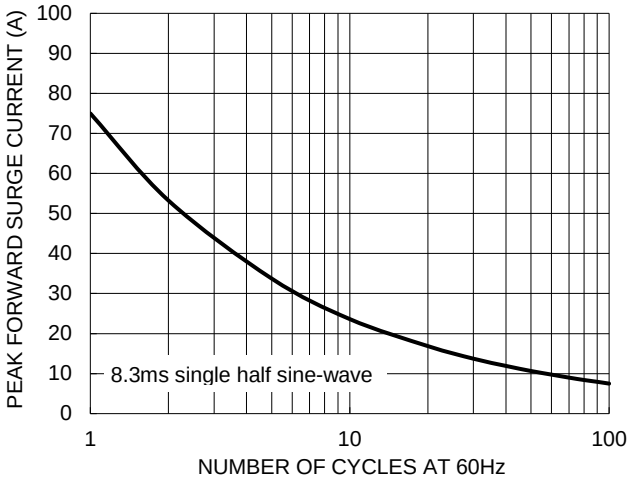


Figure 3. Maximum Non-repetitive Surge Current

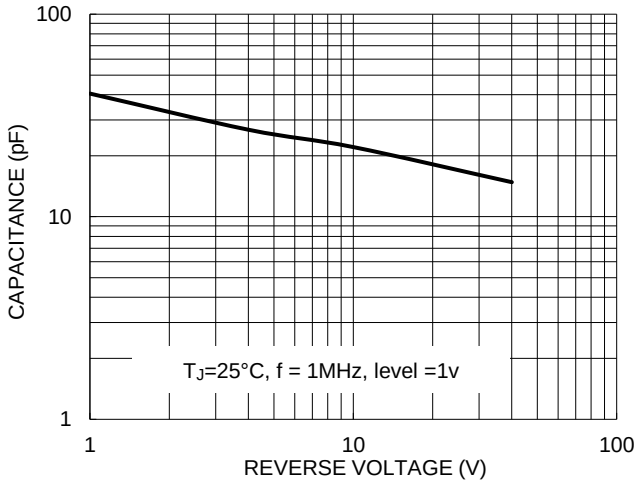


Figure 4. Typical Junction Capacitance

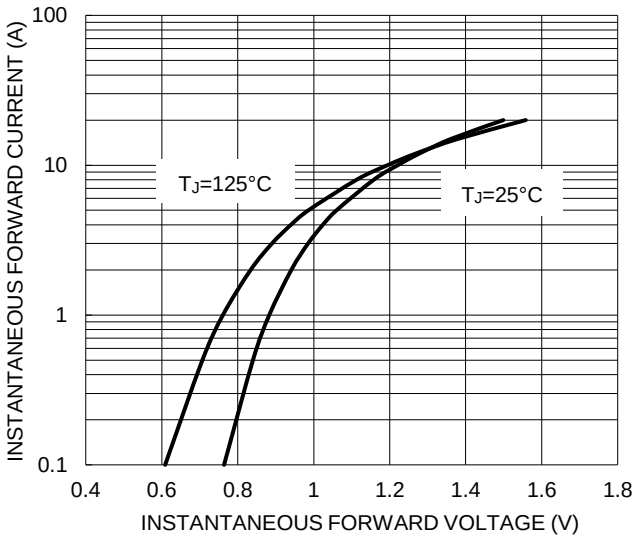


Figure 5. Typical Forward Characteristics

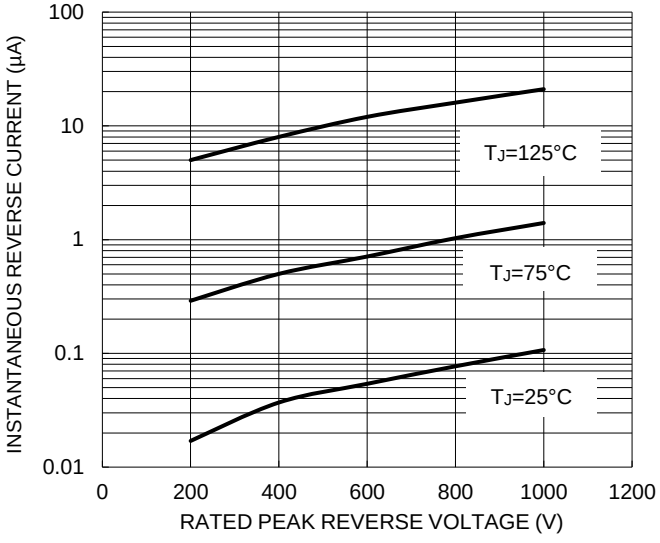
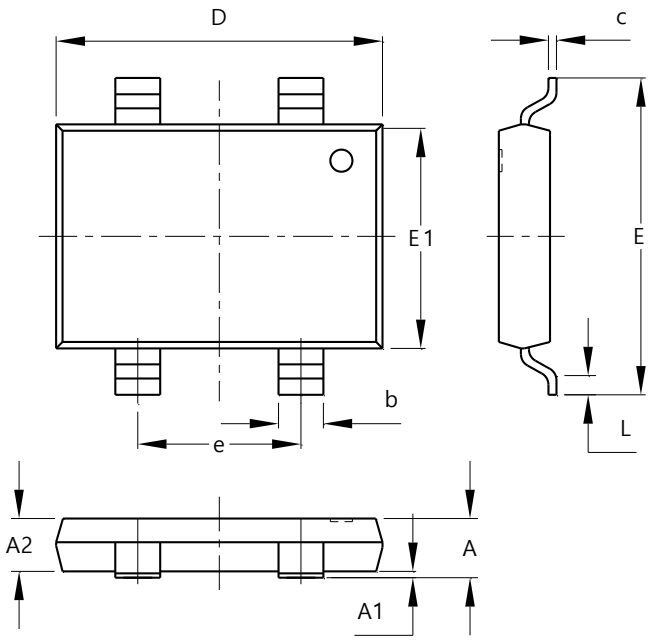


Figure 6.Typical Reverse Characteristics

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

TTL

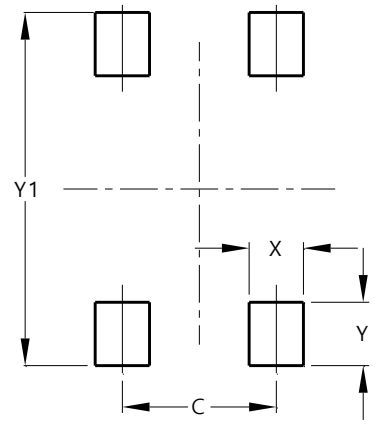


TTL			
Dim	**Min**	**Max**	**TYP**
A	1.45	1.80	1.65
A1	0.00	0.15	0.10
A2	1.45	1.65	1.55
b	1.30	1.50	1.40
c	0.15	0.35	0.25
D	10.05	10.35	10.20
E	9.75	10.05	9.90
E1	6.85	7.15	7.00
e	4.90	5.10	5.00
L	0.45	0.95	0.70
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

TTL



Dimensions	Value (in mm)
C	5.00
X	1.80
Y	2.10
Y1	11.70

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